

AMPMODU | Modu Connector System

TE Internal #: 7-534206-5 PCB Mount Receptacle, Vertical, Board-to-Board, 50 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System

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PCB Connector Assembly Type: PCB Mount Receptacle

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 50

Number of Rows: 2

Features

connectivity

Product Type Features

| Applied Pressure | Standard |
|-----------------------------------|-----------------------|
| PCB Connector Assembly Type | PCB Mount Receptacle |
| Connector System | Board-to-Board |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |
| Stackable | Yes |
| PCB Mount Orientation | Vertical |
| Number of Positions | 50 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Parallel |
| Electrical Characteristics | |
| Insulation Resistance | 5000 ΜΩ |
| Operating Voltage | 333 VAC |

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Body Features

| Connector Profile | Standard |
|--|-----------------------|
| Primary Product Color | Black |
| Contact Features | |
| Contact Protection Type | Closed Entry Housing |
| Mating Square Post Dimension | .64 mm[.025 in] |
| | 150 µin |
| Contact Shape & Form | Square |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .762 μm[30 μin] |
| Contact Type | Socket |
| Contact Current Rating (Max) | 2 A |
| Termination Features | |
| Rectangular Termination Post & Tail Thickness | .2 mm[.008 in] |
| Rectangular Termination Post & Tail Width | .69 mm[.027 in] |
| Termination Post & Tail Length | 2.92 mm[.115 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Mating Entry Location | Тор |
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Material | Polyester - GF |
| Dimensions | |
| Connector Height | 5.03 mm[.198 in] |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| Stack Height | 10.92 mm[.43 in] |
| | |

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| PCB Thickness (Recommended) | 1.57 mm[.055 – .094 in] |
|-----------------------------|----------------------------|
| Usage Conditions | |
| Housing Temperature Rating | Standard |
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |
| Operation/Application | |
| Solder Process Feature | Board Standoff |
| Circuit Application | Signal |
| Industry Standards | |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Quantity | 9 |
| Packaging Type | Box, Tube |
| | |

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU

Compliant

| EU ELV Directive 2000/53/EC | Compliant |
|---|---|
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | Not Low Halogen - contains Br or Cl > 900 ppm. |
| Solder Process Capability | Wave solder capable to 240°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides

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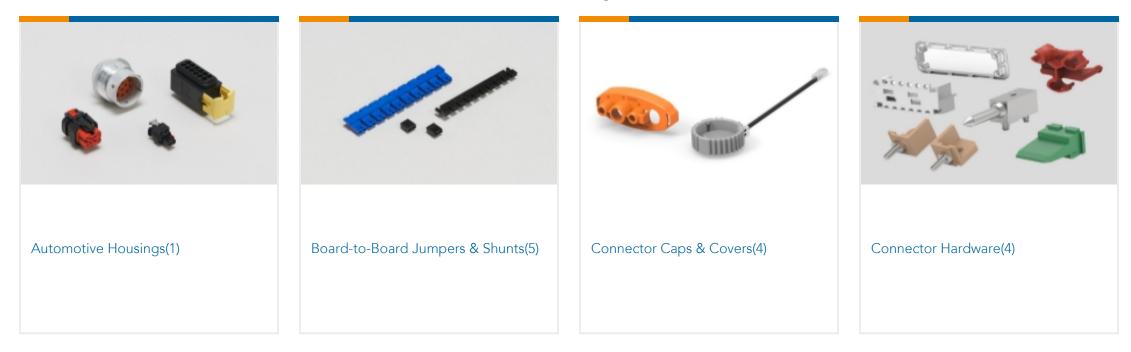


on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts



Also in the Series | Modu Connector System





Customers Also Bought



PCB Mount Receptacle, Vertical, Board-to-Board, 50 Position, 2.54 mm [.1 in] Centerline, Gold, Through Hole - Solder, Signal, Modu Connector System





Documents

Product Drawings 50 MODII VRT DR CE 100/115

English

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_7-534206-5_N.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_7-534206-5_N.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_7-534206-5_N.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications Application Specification

English

Product Environmental Compliance MD_7-534206-5_091720152018_dmtec

English

MD_7-534206-5_091720152018_dmtec

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